

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0736443017](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location A, Polarizing Key Position N/A, 144 Circuits

Documents:

3D Model	Drawing (PDF)
Test Summary (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

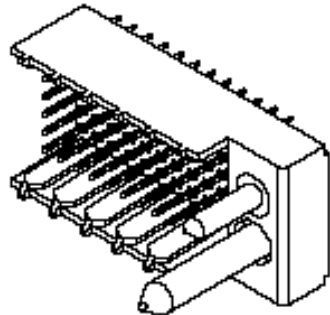
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit, Tin/Lead (SnPb)
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	None
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness Recommended (in)	0.098 In
PCB Thickness Recommended (mm)	2.50 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.375



Series

image - Reference only

EU RoHS

RoHS Compliant by Exemption

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73644Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
HDM® Backplane	0622005703
Insertion Head for	
144 Positions	

Polarized to PCB	No	Extraction Tool	0621001000
Stackable	No		
Surface Mount Compatible (SMC)	Yes		
Temperature Range - Operating	-55°C to +105°C		
Termination Interface: Style	Through Hole - Compliant Pin		
Electrical			
Current - Maximum per Contact	1A		
Data Rate	1.0 Gbps		
Real Signals (per 25mm)	75		
Shielded	No		
Voltage - Maximum	250V AC		
Material Info			
Reference - Drawing Numbers			
Packaging Specification	PK-70873-0818		
Sales Drawing	SDA-73644-****		

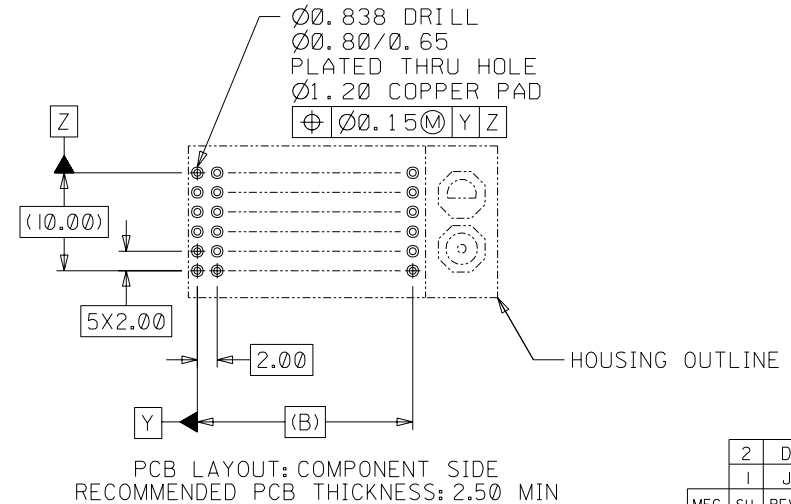
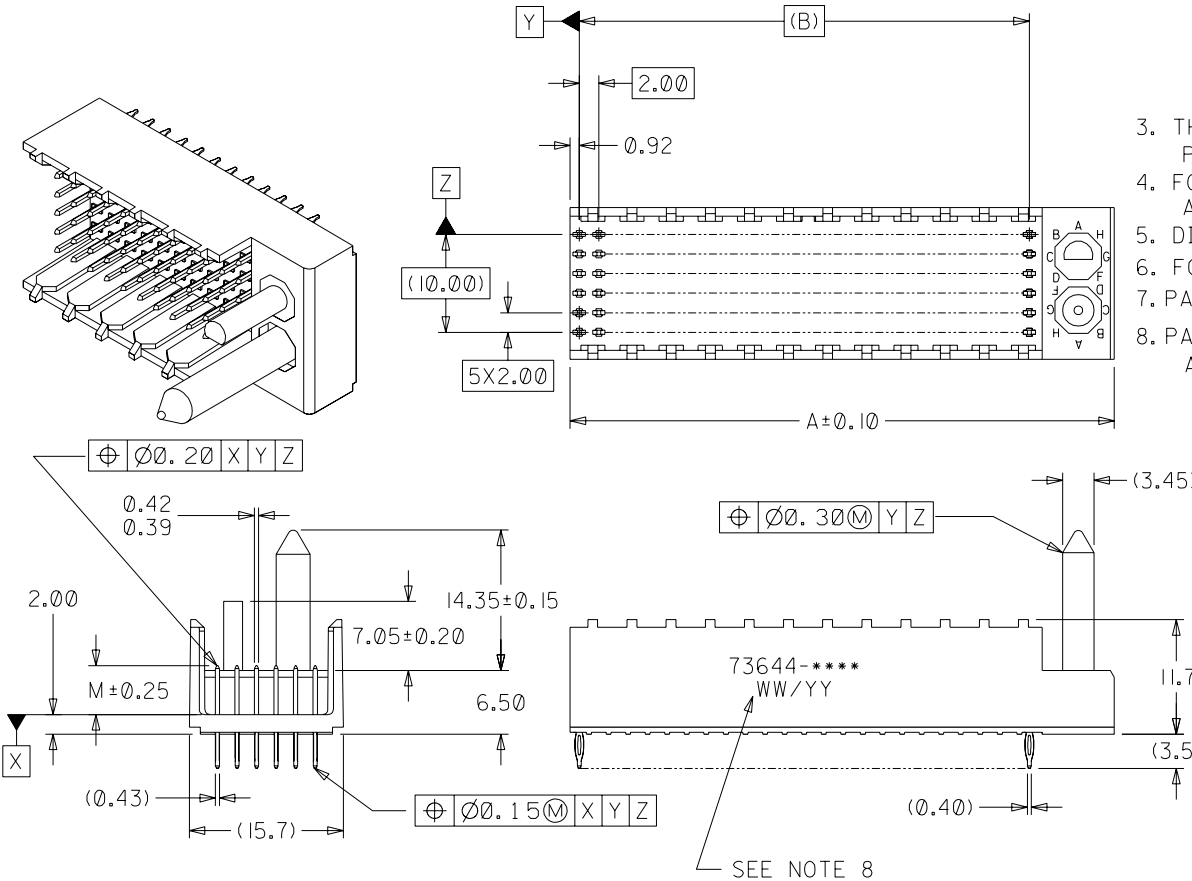
HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 05/14/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MIN. THICKNESS; SELECTIVE TIN/LEAD (Sb/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. DIMENSIONS ARE IN MILLIMETERS.
6. FOR SPECIFIC MATERIAL NUMBERS, REFER TO SHEET 2.
7. PACKAGE PER PK-70873-0818.
8. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

2	D
1	J
MFG. SH.	REV.

		I	REVISED ECR UDT2000-0348 BINGHAM 99/10/12
		H	REVISED ECR UDT1999-0662 BINGHAM 99/05/18
J	REVISED ECR UCP2003-2260 THOMAS 03/04/25	G	REVISED ECR UDT1999-0476 BINGHAM 98/12/21
LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH			
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°			
		INCH	METRIC
3 PLACE	± N/A	---	---
2 PLACE	± N/A	± 0.05	± 0.05
1 PLACE	---	± 0.10	± 0.10
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY	JRR	CHK'D. BY	SMR
APP'D. BY	CAB	SCALE	2 : 1

 = 0		 = 0		REVISE ONLY ON CAD SYSTEM	
TITLE					
SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION					
 MOLEX INCORPORATED		SHEET NO.		DATE	
LISLE, ILL. 60532		1 OF 2		96/12/18	
PART NO.		DRWG. NO.			
SEE CHART		SDA-73644-*****			
FILE NAME S73644X1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			DIV. SIZE DA B

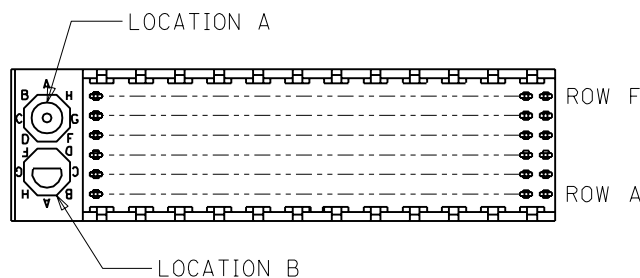
10		9	8	7	6		7364
F	MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	PLATING		DIM "A"	DIM "B"	DIM "M"
	73644-00**	72	SELECTIVE GOLD/GOLD FLASH		31.60	22.00	5.00
	73644-01**	72	SELECTIVE GOLD/GOLD FLASH		31.60	22.00	5.50
	73644-02**	72	SELECTIVE GOLD/GOLD FLASH		31.60	22.00	6.00
	73644-10**	144	SELECTIVE GOLD/GOLD FLASH		55.60	46.00	5.00
	73644-11**	144	SELECTIVE GOLD/GOLD FLASH		55.60	46.00	5.50
	73644-12**	144	SELECTIVE GOLD/GOLD FLASH		55.60	46.00	6.00
E	73644-20**	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD		31.60	22.00	5.00
	73644-21**	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD		31.60	22.00	5.50
	73644-22**	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD		31.60	22.00	6.00
	73644-30**	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD		55.60	46.00	5.00
	73644-31**	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD		55.60	46.00	5.50
	73644-32**	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD		55.60	46.00	6.00

MATERIAL NUMBER ASSIGNMENT

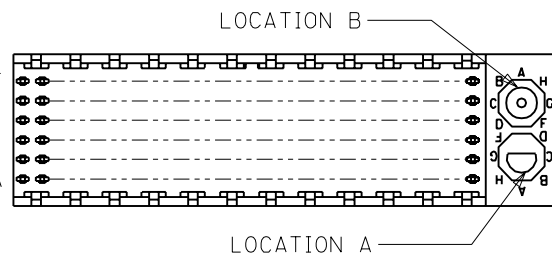
73644- * * * *

0 = 72-CIRCUIT, GOLD/GOLD FLASH
1 = 144-CIRCUIT, GOLD/GOLD FLASH
2 = 72-CIRCUIT, GOLD/TIN-LEAD
3 = 144-CIRCUIT, GOLD/TIN-LEAD

```
0 = 5.00 MATING LENGTH
1 = 5.50 MATING LENGTH
2 = 6.00 MATING LENGTH
```



REF. MATERIAL NUMBER 73644-0009
GUIDE PIN IS IN LOCATION A
POLARIZING KEY IS IN LOCATION B. POSITION F



REF. MATERIAL NUMBER 73644-0008
GUIDE PIN IS IN LOCATION B
POLARIZING KEY IS IN LOCATION A, POSITION E

NUMBER	GUIDE POST LOCATION	POLAR KEY POSITION
00	B	A
01	A	
02	B	B
03	A	
04	B	C
05	A	
06	B	D
07	A	
08	B	E
09	A	
10	B	F
11	A	
12	B	G
13	A	
14	B	H
15	A	
16	B	N/A
17	A	
18	N/A	

[illegible]

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9